SEPTEMBER 1993 - REVISED SEPTEMBER 1997

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TELECOMMUNICATION SYSTEM SECONDARY PROTECTION

 Ion-Implanted Breakdown Region Precise and Stable Voltage Low Voltage Overshoot under Surge

DEVICE	V _{DRM}	V _(BO)		
DEVICE	٧	٧		
'1072F3	- 58	- 72		
'1082F3	- 66	- 82		

- Planar Passivated Junctions
 Low Off-State Current < 10 μA
- Rated for International Surge Wave Shapes

WAVE SHAPE	STANDARD	I _{TSP} A
2/10 µs	FCC Part 68	80
8/20 µs	ANSI C62.41	70
10/160 µs	FCC Part 68	60
10/560 µs	FCC Part 68	45
0.5/700 μs	RLM 88	38
	FTZ R12	50
10/700 μs	VDE 0433	50
	CCITT IX K17/K20	50
10/1000 µs	REA PE-60	35

Surface Mount and Through-Hole Options

PACKAGE	PART # SUFFIX
Small-outline	D
Small-outline taped	DR
and reeled	DIX
Plastic DIP	Р
Single-in-line	SL

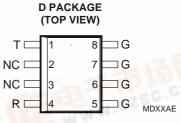
UL Recognized, E132482

description

These dual asymmetrical transient voltage suppressors are designed for the overvoltage protection of ICs used for the SLIC (Subscriber Line Interface Circuit) function. The IC line driver section is typically powered with 0 V and a negative supply. The TISP1xxxF3 limits voltages that exceed these supply rails and is offered in two voltage variants to match typical negative supply voltage values.

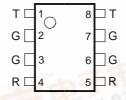
High voltages can occur on the line as a result of exposure to lightning strikes and a.c. power surges. Negative transients are initially limited by breakdown clamping until the voltage rises to the

with the terms of Power Innovations standard warranty. Production processing does not



NC - No internal connection

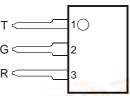
P PACKAGE (TOP VIEW)



MDXXA

Specified T terminal ratings require connection of pins 1 and 8. Specified R terminal ratings require connection of pins 4 and 5.

SL PACKAGE (TOP VIEW)



MDXXAG MD1X

device symbol



Terminals T, R and G correspond to the alternative line designators of A, B and C

breakover level, which causes the device to crowbar. The high crowbar holding current prevents d.c. latchup as the current subsides. Positive transients are limited by diode forward conduction. These protectors are guaranteed to suppress and withstand the listed international lightning surges on any terminal pair



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description (continued)

These monolithic protection devices are fabricated in ion-implanted planar structures to ensure precise and matched breakover control and are virtually transparent to the system in normal operation

The small-outline 8-pin assignment has been carefully chosen for these devices to maximise the inter-pin clearance and creepage distances which are used by standards (e.g. IEC950) to establish voltage withstand ratings.

absolute maximum ratings

RATING			VALUE	UNIT
Repetitive peak off-state voltage (0°C < T _J <70°C)	V_{DRM}	-58 -66	V	
Non-repetitive peak on-state pulse current (see Notes 1, 2 and 3)				
1/2 μs (Gas tube differential transient, open-circuit voltage wave shape		120		
2/10 μs (FCC Part 68, open-circuit voltage wave shape 2/10 μs)			80	
8/20 μs (ANSI C62.41, open-circuit voltage wave shape 1.2/50 μs)			70	
10/160 μs (FCC Part 68, open-circuit voltage wave shape 10/160 μs)			60	
5/200 μs (VDE 0433, open-circuit voltage wave shape 2 kV, 10/700 μs)	I _{TSP}	50	Α
0.2/310 μs (RLM 88, open-circuit voltage wave shape 1.5 kV, 0.5/700 μ	ıs)		38	
5/310 μs (CCITT IX K17/K20, open-circuit voltage wave shape 2 kV, 10	0/700 μs)		50	
5/310 μs (FTZ R12, open-circuit voltage wave shape 2 kV, 10/700 μs)			50	
10/560 μs (FCC Part 68, open-circuit voltage wave shape 10/560 μs)			45	
10/1000 μs (REA PE-60, open-circuit voltage wave shape 10/1000 μs)			35	
Non-repetitive peak on-state current (see Notes 2 and 3)	D Package		4	
50 Hz, 1 s	P Package	I_{TSM}	6	A rms
SL P			6	
Initial rate of rise of on-state current, Linear current ramp, Maximum ramp value < 38 A			250	A/µs
Junction temperature			-40 to +150	°C
Storage temperature range		T _{stg}	-40 to +150	°C

- NOTES: 1. Further details on surge wave shapes are contained in the Applications Information section.
 - 2. Initially the TISP must be in thermal equilibrium with 0°C < T_J <70°C. The surge may be repeated after the TISP returns to its initial conditions.
 - 3. Above 70°C, derate linearly to zero at 150°C lead temperature.

electrical characteristics for the T and R terminals, 25°C (unless otherwise noted)

			_	TI	SP1072	F3	TI	SP1082	F3	
	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNIT
I _{DRM}	Repetitive peak off- state current	$V_D = \pm V_{DRM}$, 0°C < T_J <70°C				±10			±10	μA
I _D	Off-state current	$V_D = \pm 50 \text{ V}$				±10			±10	μA
		$f = 100 \text{ kHz}, V_d = 100 \text{ mV}$	D Package		0.08	0.5		0.08	0.5	pF
C_{off}	Off-state capacitance	$V_D = 0$	P Package		0.06	0.4		0.06	0.4	pF
		(see Note 4)	SL Package		0.02	0.3		0.02	0.3	pF

NOTE 4: Further details on capacitance are given in the Applications Information section.

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electrical characteristics for the T and G and R and G terminals, 25°C (unless otherwise noted)

		TEST CONDITIONS		TI	SP1072	F3	TI	SP1082	F3	
	PARAMETER			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
I _{DRM}	Repetitive peak off- state current	$V_D = V_{DRM}$, 0°C < T_J <70°C				-10			-10	μA
V _(BO)	Breakover voltage	$dv/dt = -250 \text{ V/ms}, R_{SOURCE} = 3$	300 Ω			-72			-82	V
V _(BO)	Impulse breakover voltage	dv/dt = -1000 V/ μ s, R _{SOURCE} = 50 Ω , di/dt < -20 A/ μ s			-78			-92		V
I _(BO)	Breakover current	$dv/dt = -250 \text{ V/ms}, R_{SOURCE} = 300 \Omega$		-0.1		-0.6	-0.1		-0.6	Α
V _{FRM}	Peak forward recovery voltage	$dv/dt = 1000 \text{ V/}\mu\text{s}, R_{SOURCE} = 5$ $di_F/dt < 20 \text{ A/}\mu\text{s}$	0 Ω,		3.3			3.3		V
V _F	Forward voltage	$I_T = 5 \text{ A}, t_W = 100 \mu\text{s}$				3			3	V
V _T	On-state voltage	$I_T = -5 \text{ A}, t_W = 100 \mu\text{s}$				-3			-3	V
I _H	Holding current	di/dt = +30 mA/ms		-0.15			-0.15			Α
dv/dt	Critical rate of rise of off-state voltage	Linear voltage ramp Maximum ramp value < 0.85V _{DRN}	1	-5			-5			kV/μs
I _D	Off-state current	V _D = -50 V				-10			-10	μA
C _{off}	Off-state capacitance	$f = 100 \text{ kHz}, V_d = 100 \text{ mV}$ Third terminal voltage = 0	$V_D = 0,$ $V_D = -5 \text{ V}$		150 65	240 104		130 55	240 104	pF pF
	·	(see Note 5)	$V_D = -50 \text{ V}$		30	48		25	48	pF

NOTE 5: Further details on capacitance are given in the Applications Information section.

thermal characteristics

	PARAMETER	TEST CONDITIONS			TYP	MAX	UNIT
		P _{tot} = 0.8 W, T _A = 25°C	D Package			160	
$R_{\theta JA}$	$R_{\theta JA}$ Junction to free air thermal resistance	5 cm ² , FR4 PCB	P Package			100	°C/W
		o ciii , i ka i ob	SL Package			105	



PARAMETER MEASUREMENT INFORMATION

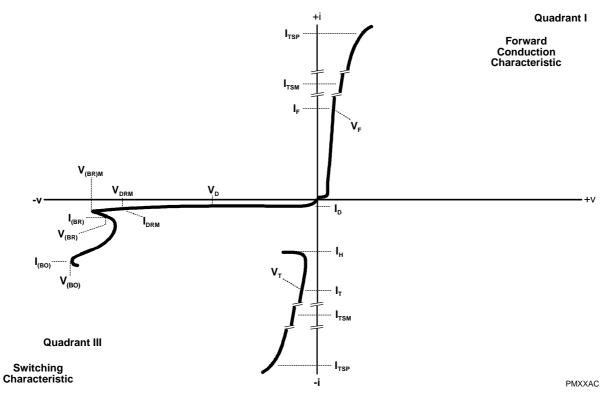


Figure 1. VOLTAGE-CURRENT CHARACTERISTIC FOR TERMINALS R AND G OR T AND G

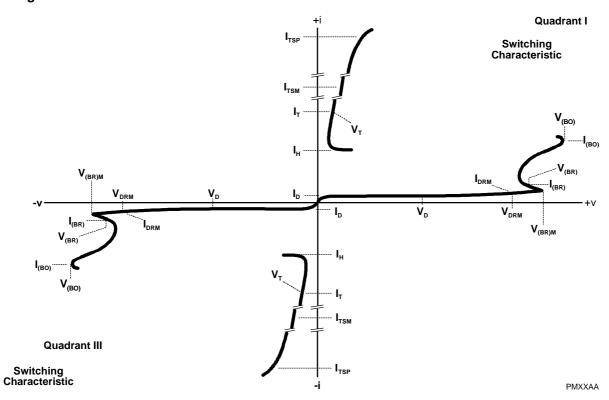
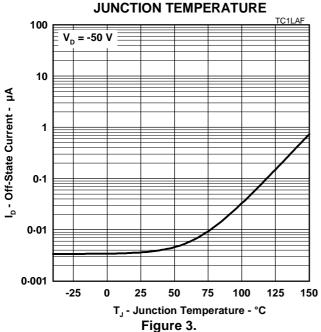


Figure 2. VOLTAGE-CURRENT CHARACTERISTIC FOR TERMINALS R AND T

TYPICAL CHARACTERISTICS R and G, or T and G terminals

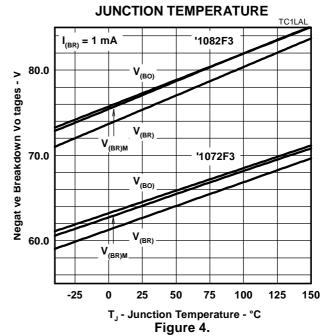
OFF-STATE CURRENT

VS



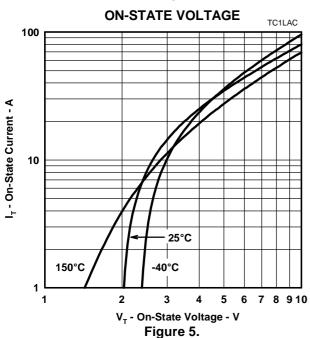
BREAKDOWN VOLTAGES

vs



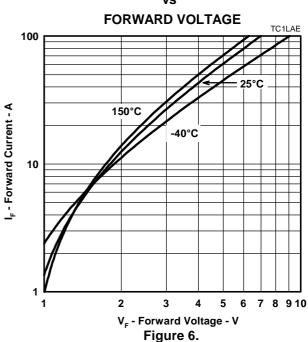
ON-STATE CURRENT

vs



FORWARD CURRENT

VS

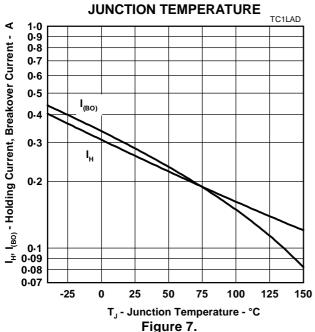




TYPICAL CHARACTERISTICS R and G, or T and G terminals

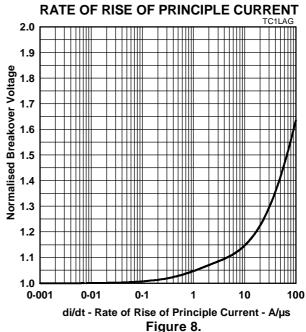
HOLDING CURRENT & BREAKOVER CURRENT

VS



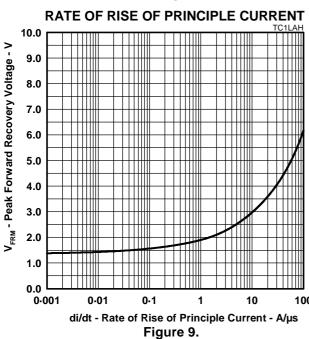
NORMALISED BREAKOVER VOLTAGE vs

73



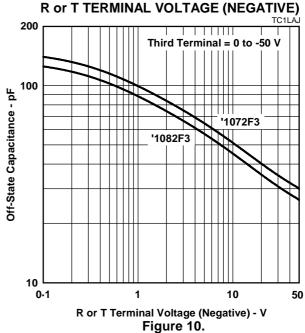
PEAK FORWARD RECOVERY VOLTAGE

٧S



OFF-STATE CAPACITANCE

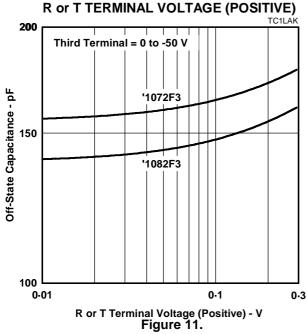
VS SETTERMINAL VOLTAGE (N



TYPICAL CHARACTERISTICS R and G, or T and G terminals

vs or T TERMINAL VOLTAGE (POSITIVE)

OFF-STATE CAPACITANCE



OFF-STATE CAPACITANCE vs

NOTION TEMPER

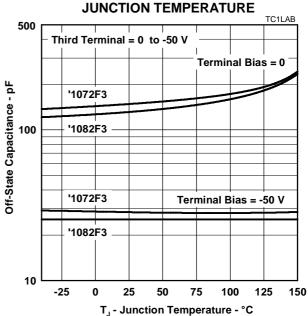


Figure 12.

SURGE CURRENT

DECAY TIME

TC1LAA

TC

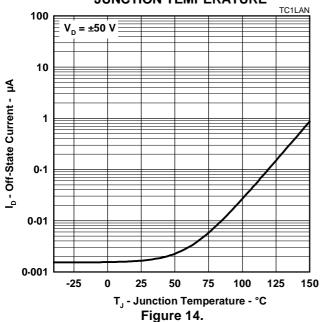


TYPICAL CHARACTERISTICS R and T terminals

OFF-STATE CURRENT

vs

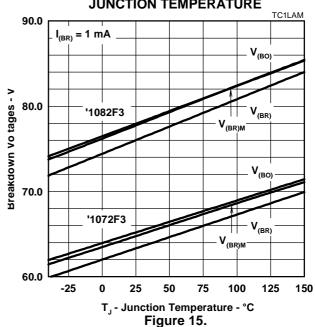
JUNCTION TEMPERATURE



BREAKDOWN VOLTAGES

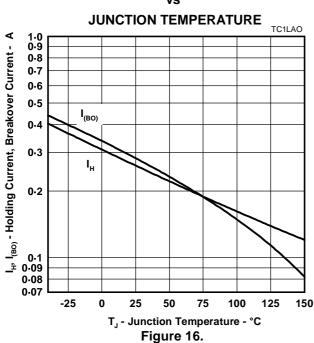
vs

JUNCTION TEMPERATURE



HOLDING CURRENT & BREAKOVER CURRENT

vs



NORMALISED BREAKOVER VOLTAGE

vs

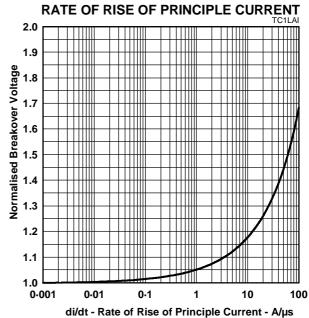
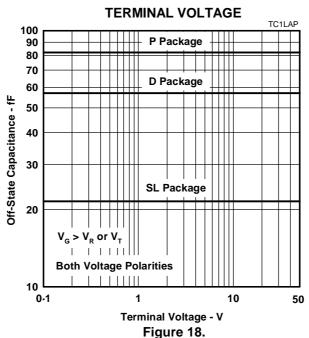


Figure 17.

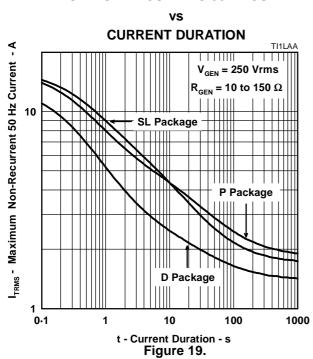
TYPICAL CHARACTERISTICS R and T terminals OFF-STATE CAPACITANCE

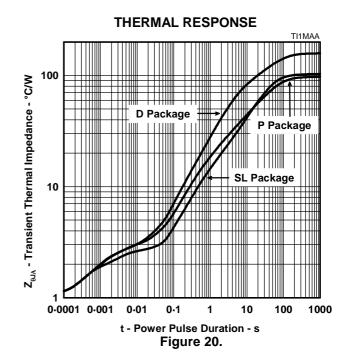
VS



THERMAL INFORMATION

MAXIMUM NON-RECURRING 50 Hz CURRENT







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APPLICATIONS INFORMATION

electrical characteristics

The electrical characteristics of a TISP are strongly dependent on junction temperature, T_J . Hence a characteristic value will depend on the junction temperature at the instant of measurement. The values given in this data sheet were measured on commercial testers, which generally minimise the temperature rise caused by testing. Application values may be calculated from the parameters' temperature coefficient, the power dissipated and the thermal response curve Z_θ (see M. J. Maytum, "Transient Suppressor Dynamic Parameters."TI Technical Journal, vol. 6, No. 4, pp.63-70, July-August 1989).

lightning surge

wave shape notation

Most lightning tests, used for equipment verification, specify a unidirectional sawtooth waveform which has an exponential rise and an exponential decay. Wave shapes are classified in terms of peak amplitude (voltage or current), rise time and a decay time to 50% of the maximum amplitude. The notation used for the wave shape is *amplitude*, *rise time/decay time*. A 50A, 5/310 µs wave shape would have a peak current value of 50 A, a rise time of 5 µs and a decay time of 310 µs. The TISP surge current graph comprehends the wave shapes of commonly used surges.

generators

There are three categories of surge generator type, single wave shape, combination wave shape and circuit defined. Single wave shape generators have essentially the same wave shape for the open circuit voltage and short circuit current (e.g. 10/1000 µs open circuit voltage and short circuit current). Combination generators have two wave shapes, one for the open circuit voltage and the other for the short circuit current (e.g. 1.2/50 µs open circuit voltage and 8/20 µs short circuit current) Circuit specified generators usually equate to a combination generator, although typically only the open circuit voltage waveshape is referenced (e.g. a 10/700 µs open circuit voltage generator typically produces a 5/310 µs short circuit current). If the combination or circuit defined generators operate into a finite resistance the wave shape produced is intermediate between the open circuit and short circuit values.

current rating

When the TISP switches into the on-state it has a very low impedance. As a result, although the surge wave shape may be defined in terms of open circuit voltage, it is the current wave shape that must be used to assess the required TISP surge capability. As an example, the CCITT IX K17 1.5 kV, $10/700~\mu s$ surge is changed to a 38 A, $5/310~\mu s$ waveshape when driving into a short circuit. Thus the TISP surge current capability, when directly connected to the generator, will be found for the CCITT IX K17 waveform at 310 μs on the surge graph and not 700 μs . Some common short circuit equivalents are tabulated below:

STANDARD	OPEN CIRCUIT VOLTAGE	SHORT CIRCUIT CURRENT
CCITT IX K17	1.5 kV, 10/700 µs	38 A, 5/310 µs
CCITT IX K20	1 kV, 10/700 µs	25 A, 5/310 µs
RLM88	1.5 kV, 0.5/700 µs	38 A, 0.2/310 µs
VDE 0433	2.0 kV, 10/700 µs	50 A, 5/200 µs
FTZ R12	2.0 kV, 10/700 µs	50 A, 5/310 µs

Any series resistance in the protected equipment will reduce the peak circuit current to less than the generators' short circuit value. A 2 kV open circuit voltage, 50 A short circuit current generator has an effective output impedance of 40 Ω (2000/50). If the equipment has a series resistance of 25 Ω then the surge current requirement of the TISP becomes 31 A (2000/65) and not 50 A.

APPLICATIONS INFORMATION

protection voltage

The protection voltage, $(V_{(BO)})$, increases under lightning surge conditions due to thyristor regeneration. This increase is dependent on the rate of current rise, di/dt, when the TISP is clamping the voltage in its breakdown region. The $V_{(BO)}$ value under surge conditions can be estimated by multiplying the 50 Hz rate $V_{(BO)}$ (250 V/ms) value by the normalised increase at the surge's di/dt (Figure 8.) . An estimate of the di/dt can be made from the surge generator voltage rate of rise, dv/dt, and the circuit resistance.

As an example, the CCITT IX K17 1.5 kV, 10/700 μ s surge has an average dv/dt of 150 V/ μ s, but, as the rise is exponential, the initial dv/dt is higher, being in the region of 450 V/ μ s. The instantaneous generator output resistance is 25 Ω . If the equipment has an additional series resistance of 20 Ω , the total series resistance becomes 45 Ω . The maximum di/dt then can be estimated as 450/45 = 10 A/ μ s. In practice the measured di/dt and protection voltage increase will be lower due to inductive effects and the finite slope resistance of the TISP breakdown region.

capacitance

off-state capacitance

The off-state capacitance of a TISP is sensitive to junction temperature, T_J , and the bias voltage, comprising of the dc voltage, V_D , and the ac voltage, V_d . All the capacitance values in this data sheet are measured with an ac voltage of 100 mV. The typical 25°C variation of capacitance value with ac bias is shown in Figure 21. When $V_D >> V_d$ the capacitance value is independent on the value of V_d . The capacitance is essentially constant over the range of normal telecommunication frequencies.

NORMALISED CAPACITANCE

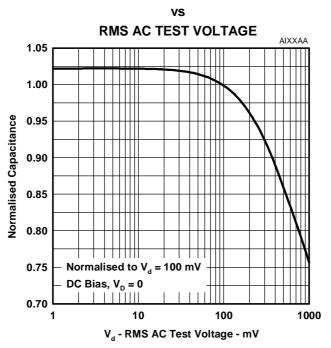


Figure 21.



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APPLICATIONS INFORMATION

longitudinal balance

Figure 22 shows a three terminal TISP with its equivalent "delta" capacitance Each capacitance, C_{TG} , C_{RG} and C_{TR} , is the true terminal pair capacitance measured with a three terminal or guarded capacitance bridge. If wire R is biased at a larger potential than wire T then $C_{TG} > C_{RG}$. Capacitance C_{TG} is equivalent to a capacitance of C_{RG} in parallel with the capacitive difference of $(C_{TG} - C_{RG})$. The line capacitive unbalance is due to $(C_{TG} - C_{RG})$ and the capacitance shunting the line is $C_{TR} + C_{RG}/2$.

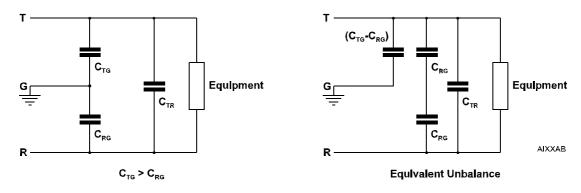


Figure 22.

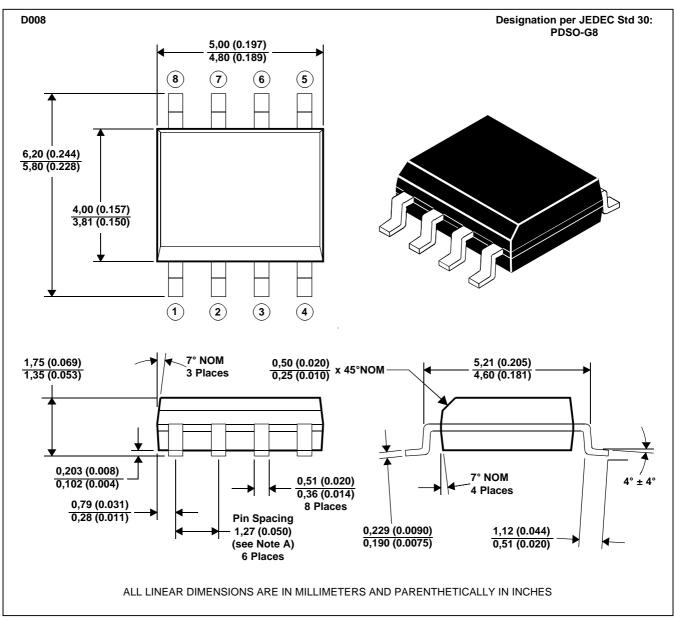
All capacitance measurements in this data sheet are three terminal guarded to allow the designer to accurately assess capacitive unbalance effects. Simple two terminal capacitance meters (unguarded third terminal) give false readings as the shunt capacitance via the third terminal is included.

MECHANICAL DATA

D008

plastic small-outline package

This small-outline package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. Leads are within 0,25 (0.010) radius of true position at maximum material condition.

- B. Body dimensions do not include mold flash or protrusion.
- C. Mold flash or protrusion shall not exceed 0,15 (0.006).
- D. Lead tips to be planar within ±0,051 (0.002).

MDXXAA

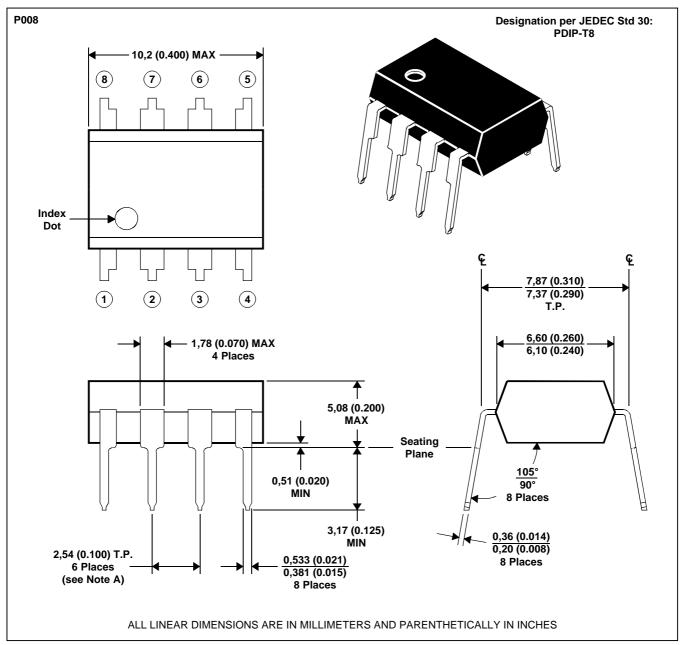


MECHANICAL DATA

P008

plastic dual-in-line package

This dual-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. The package is intended for insertion in mounting-hole rows on 7,62 (0.300) centers. Once the leads are compressed and inserted, sufficient tension is provided to secure the package in the board during soldering. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: Each pin centerline is located within 0,25 (0.010) of its true longitudinal position

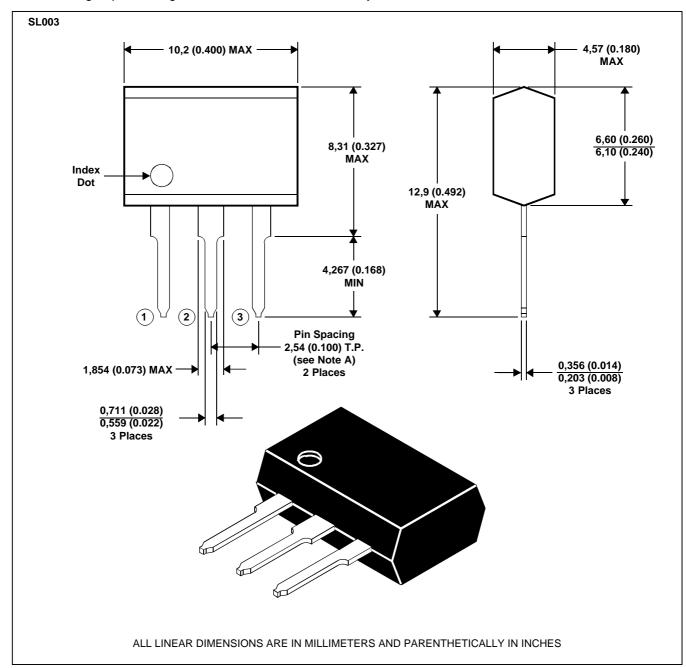
MDXXABA

MECHANICAL DATA

SL003

3-pin plastic single-in-line package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. Each pin centerline is located within 0,25 (0.010) of its true longitudinal position.

B. Body molding flash of up to 0,15 (0.006) may occur in the package lead plane.

MDXXAD

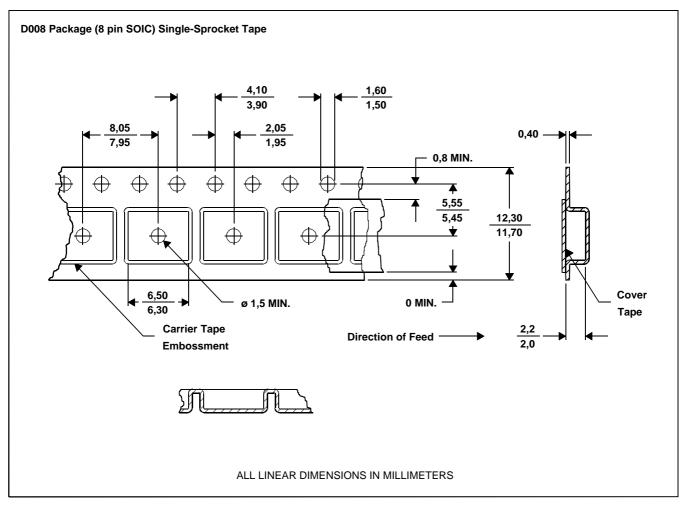


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MECHANICAL DATA

D008

tape dimensions



NOTES: A. Taped devices are supplied on a reel of the following dimensions:-

MDXXAT

Reel diameter: 330 +0,0/-4,0 mm Reel hub diameter: 100 \pm 2,0 mm Reel axial hole: 13,0 \pm 0,2 mm

B. 2500 devices are on a reel.

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